### 1.5A Ultra-Small Controlled Load Switch with Auto-Discharge Path

The NCP432 and NCP433 are a low Ron MOSFET controlled by external logic pin, allowing optimization of battery life, and portable device autonomy.

Indeed, due to a current consumption optimization with PMOS structure, leakage currents are eliminated by isolating connected IC's on the battery when not used.

Output discharge path is also embedded to eliminate residual voltages on the output (NCP433 only).

Proposed in wide input voltage range from 1.0 V to 3.6 V , and a very small $0.76 \times 0.76 \mathrm{~mm}$ WLCSP4, 0.4 mm pitch.

## Features

- $1 \mathrm{~V}-3.6 \mathrm{~V}$ Operating Range
- $50 \mathrm{~m} \Omega$ P MOSFET at 1.8 V
- DC Current up to 1.5 A
- Output Auto-discharge (NCP433)
- Active High EN Pin
- WLCSP4 $0.76 \times 0.76 \mathrm{~mm}$
- These Devices are $\mathrm{Pb}-$ Free, Halogen Free/BFR Free and are RoHS Compliant


## Typical Applications

- Mobile Phones
- Tablets
- Digital Cameras
- GPS
- Portable Devices

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MARKING DIAGRAM

(Top View)

## ORDERING AND MARKING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.


Figure 1. Typical Application Circuit

PIN FUNCTION DESCRIPTION

| Pin Name | Pin Number | Type | Description |
| :---: | :---: | :---: | :--- |
| IN | A2 | POWER | Load-switch input voltage; connect a $1 \mu$ F or greater ceramic capacitor from IN to GND <br> as close as possible to the IC. |
| GND | B1 | POWER | Ground connection. |
| EN | B2 | INPUT | Enable input, logic high turns on power switch. |
| OUT | A1 | OUTPUT | Load-switch output; connect a $1 \mu \mathrm{~F}$ ceramic capacitor from OUT to GND as close as <br> possible to the IC is recommended. |

## BLOCK DIAGRAM



Figure 2. Block Diagram

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
| :---: | :---: | :---: | :---: |
| IN, OUT, EN, Pins: | $\begin{aligned} & \mathrm{V}_{\mathrm{EN}}, \mathrm{~V}_{\mathrm{IN}}, \\ & \mathrm{~V}_{\mathrm{OUT}} \end{aligned}$ | -0.3 to +4.0 | V |
| From IN to OUT Pins: Input/Output | $\mathrm{V}_{\mathrm{IN}}$, $V_{\text {OUT }}$ | 0 to + 4.0 | V |
| Maximum Junction Temperature | $\mathrm{T}_{\mathrm{J}}$ | -40 to +125 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range | $\mathrm{T}_{\text {STG }}$ | -40 to +150 | ${ }^{\circ} \mathrm{C}$ |
| Human Body Model (HBM) ESD Rating are (Notes 1 and 2) | ESD HBM | 7000 | V |
| Machine Model (MM) ESD Rating are (Notes 1 and 2) | ESD MM | 250 | V |
| Charge Device Model (CDM) ESD Rating are (Notes 1 and 2) | ESD CDM | 2000 | V |
| Latch-up protection (Note 3) <br> - Pins IN, OUT, EN | LU | 100 | mA |
| Moisture Sensitivity (Note 4) | MSL | Level 1 |  |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. According to JEDEC standard JESD22-A108.
2. This device series contains ESD protection and passes the following tests:

Human Body Model (HBM) $\pm 7.0 \mathrm{kV}$ per JEDEC standard: JESD22-A114 for all pins.
Machine Model (MM) $\pm 250$ V per JEDEC standard: JESD22-A115 for all pins.
Charge Device Model (CDM) $\pm 2.0$ kV per JEDEC standard: JESD22-C101 for all pins.
3. Latch up Current Maximum Rating: $\pm 100 \mathrm{~mA}$ per JEDEC standard: JESD78 class II.
4. Moisture Sensitivity Level (MSL): 1 per IPC/JEDEC standard: J-STD-020.

## OPERATING CONDITIONS

| Symbol | Parameter | Conditions |  | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {IN }}$ | Operational Power Supply |  |  | 1.0 |  | 3.6 | V |
| $\mathrm{V}_{\mathrm{EN}}$ | Enable Voltage |  |  | 0 |  | 3.6 |  |
| $\mathrm{T}_{\mathrm{A}}$ | Ambient Temperature Range |  |  | -40 | 25 | +85 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{C}_{\text {IN }}$ | Decoupling input capacitor |  |  | 1 |  |  | $\mu \mathrm{F}$ |
| Cout | Decoupling output capacitor |  |  | 1 |  |  | $\mu \mathrm{F}$ |
| $\mathrm{R}_{\text {өJA }}$ | Thermal Resistance Junction to Air | WLCSP package (Note 5) |  |  | 150 |  | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Iout | Maximum DC current |  |  |  |  | 1.5 | A |
| $\mathrm{P}_{\mathrm{D}}$ | Power Dissipation Rating (Note 6) | $\mathrm{T}_{\mathrm{A}} \leq 25^{\circ} \mathrm{C}$ | WLCSP package |  | 0.5 |  | W |
|  |  | $\mathrm{T}_{\mathrm{A}}=85^{\circ} \mathrm{C}$ | WLCSP package |  | 0.2 |  | W |

5. The $R_{\theta J A}$ is dependent of the PCB heat dissipation and thermal via.
6. The maximum power dissipation $\left(P_{D}\right)$ is given by the following formula:

ELECTRICAL CHARACTERISTICS Min \& Max Limits apply for $\mathrm{T}_{\mathrm{A}}$ between $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ for $\mathrm{V}_{\text {IN }}$ between 1.0 V to 3.6 V (Unless otherwise noted). Typical values are referenced to $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ and $\mathrm{V}_{\mathrm{IN}}=3.3 \mathrm{~V}$ (Unless otherwise noted).

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
| :--- | :--- | :--- | :--- | :--- | :--- | :--- |

POWER SWITCH

| $\mathrm{R}_{\mathrm{DS} \text { (on) }}$ | Static drain-source onstate resistance |  | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{I}=200 \mathrm{~mA}$ (Note 8) |  | 35 |  | $\mathrm{m} \Omega$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | $\mathrm{V}_{\text {IN }}=3.6 \mathrm{~V}$ | $\mathrm{T}_{\mathrm{A}}=85^{\circ} \mathrm{C}$ |  |  | 55 |  |
|  |  |  | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{l}=200 \mathrm{~mA}$ |  | 37 |  |  |
|  |  | $\checkmark$ | $\mathrm{T}_{\mathrm{A}}=85^{\circ} \mathrm{C}$ |  |  | 60 |  |
|  |  | $\mathrm{V}_{\mathrm{IN}}=1.8 \mathrm{~V}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{I}=200 \mathrm{~mA}$ |  | 50 |  |  |
|  |  | $\mathrm{V}_{\text {IN }}=1.8 \mathrm{~V}$ | $\mathrm{T}_{\mathrm{A}}=85^{\circ} \mathrm{C}$ |  |  | 80 |  |
|  |  | $\mathrm{V}_{\mathrm{IN}}=1.2 \mathrm{~V}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{l}=200 \mathrm{~mA}$ |  | 100 |  |  |
|  |  |  | $\mathrm{T}_{\mathrm{A}}=85^{\circ} \mathrm{C}$ |  |  | 150 |  |
|  |  | $\mathrm{V}_{\text {IN }}=1.1 \mathrm{~V}$ | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{I}=100 \mathrm{~mA}$ |  | 120 |  |  |
| $\mathrm{R}_{\text {DIS }}$ | Output discharge path | EN = low | $\mathrm{V}_{\text {IN }}=3.3 \mathrm{~V}$, NCP433 only | 40 | 65 | 90 | $\Omega$ |
| TR | Output rise time | $\mathrm{V}_{\mathrm{IN}}=3.6 \mathrm{~V}$ | $\mathrm{C}_{\text {LOAD }}=1 \mu \mathrm{~F}, \mathrm{R}_{\text {LOAD }}=25 \Omega$ (Note 7) from $10 \%$ to $90 \%$ of $V_{\text {OUT }}$ | 5 | 20 | 40 | $\mu \mathrm{S}$ |
| $\mathrm{T}_{\mathrm{F}}$ | Output fall time |  | $\begin{gathered} \mathrm{C}_{\text {LOAD }}=1 \mu \mathrm{~F}, \mathrm{R}_{\text {LOAD }}=25 \Omega \\ (\text { Note } 7) \end{gathered}$ | 20 | 56 | 80 | $\mu \mathrm{S}$ |
| Ton | Gate turn on |  | Gate turn on + Output rise time | 20 | 47 | 115 | $\mu \mathrm{S}$ |
| Ten | Enable time |  | From EN low to high to $V_{\text {OUT }} 10 \%$ | 15 | 30 | 75 | $\mu \mathrm{S}$ |
| $\mathrm{T}_{\text {dis }}$ | Disable time |  | From EN high to low to $V_{\text {OUT }}=90 \%$ of fully on | 2 | 11 | 20 | $\mu \mathrm{s}$ |
| $\mathrm{V}_{\mathrm{IH}}$ | High-level input voltage |  |  | 0.9 |  |  | V |
| $\mathrm{V}_{\mathrm{IL}}$ | Low-level input voltage |  |  |  |  | 0.5 | V |

## QUIESCENT CURRENT

| $\mathrm{I}_{\mathrm{Q}}$ | Current consumption | $\mathrm{V}_{\mathrm{IN}}=3.3 \mathrm{~V}, \mathrm{EN}=$ low, No load |  | 0.01 | 0.6 |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | $\mathrm{~V}_{\mathrm{IN}}=3.3 \mathrm{~V}, \mathrm{EN}=$ high, No load | 0.2 | 0.6 | $\mu \mathrm{~A}$ |

7. Parameters are guaranteed for $\mathrm{C}_{\text {LOAD }}$ and R ROAD connected to the OUT pin with respect to the ground 8. Guaranteed by design and characterization, not production tested.

## TIMINGS



Figure 3. Enable, Rise and Fall Time

## TYPICAL CHARACTERISTICS



Figure 4. Standby Current versus Temperature


Figure 6. $\mathrm{R}_{\mathrm{DS}(\text { on })}$ versus $\mathrm{V}_{\mathrm{IN}}, 25^{\circ} \mathrm{C}, 100 \mathrm{~mA}$ Load


Figure 5. Quiescent Current versus Temperature


Figure 7. $\mathrm{R}_{\mathrm{DS}(o n)}$ versus Temperature, 100 mA Load

## FUNCTIONAL DESCRIPTION

## Overview

The NCP432 - NCP433 are high side P channel MOSFET power distribution switch designed to isolate ICs connected on the battery in order to save energy. The part can be turned on, with a range of battery from 1.0 V to 3.6 V .

## Enable Input

Enable pin is an active high. The path is opened when EN pin is tied low (disable), forcing P MOS switch off.
The IN/OUT path is activated with a minimum of Vin of 1.0 V and EN forced to high level.

## Auto Discharge (NCP433 only)

NMOS FET is placed between the output pin and GND, in order to discharge the application capacitor connected on OUT pin.

The auto-discharge is activated when EN pin is set to low level (disable state).
The discharge path ( Pull down NMOS) stays activated as long as EN pin is set at low level and $\mathrm{V}_{\text {IN }}>1.0 \mathrm{~V}$.
In order to limit the current across the internal discharge N -MOSFET, the typical value is set at $65 \Omega$.

## Cin and Cout Capacitors

IN and OUT, $1 \mu \mathrm{~F}$, at least, capacitors must be placed as close as possible the part for stability improvement.

## APPLICATION INFORMATION

## Power Dissipation

Main contributor in term of junction temperature is the power dissipation of the power MOSFET. Assuming this, the power dissipation and the junction temperature in normal mode can be calculated with the following equations:

$$
\mathrm{P}_{\mathrm{D}}=\mathrm{R}_{\mathrm{DS}(\mathrm{on})} \times\left(\mathrm{I}_{\mathrm{OUT}}\right)^{2}
$$

$\mathrm{P}_{\mathrm{D}} \quad=$ Power dissipation (W)
$\mathrm{R}_{\mathrm{DS}(\mathrm{on})} \quad=$ Power MOSFET on resistance $(\Omega)$
IOUT $\quad=$ Output current (A)

$$
T_{J}=P_{D} \times R_{\theta J A}+T_{A}
$$

$\mathrm{T}_{\mathrm{J}} \quad=$ Junction temperature $\left({ }^{\circ} \mathrm{C}\right)$
$\mathrm{R}_{\text {日JA }}$
$\mathrm{T}_{\mathrm{A}}$
$=$ Package thermal resistance $\left({ }^{\circ} \mathrm{C} / \mathrm{W}\right)$
$=$ Ambient temperature $\left({ }^{\circ} \mathrm{C}\right)$

## PCB Recommendations

The NCP432 - NCP433 integrate an up to 1.5 A rated PMOS FET, and the PCB design rules must be respected to properly evacuate the heat out of the silicon. By increasing PCB area, especially around IN and OUT pins, the R $_{\theta J A}$ of the package can be decreased, allowing higher power dissipation.

## ORDERING INFORMATION

| Device | Marking | Package | Shipping $^{\dagger}$ |
| :--- | :---: | :--- | :---: |
| NCP432FCT2G | AV | WLCSP4 <br> (Pb-Free) | $3000 /$ Tape \& Reel |
| NCP433FCT2G | AT | WLCSP4 <br> (Pb-Free) | $3000 /$ Tape \& Reel |

$\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

|  | MILLIMETERS |  |
| :---: | :---: | :---: |
| DIM | MIN | MAX |
| A | 0.57 | 0.63 |
| A1 | 0.18 | 0.23 |
| A2 | 0.40 REF |  |
| $\mathbf{b}$ | 0.24 |  |
| D | 0.28 |  |
| E | 0.76 BSC |  |
| e | 0.46 BSC |  |

RECOMMENDED SOLDERING FOOTPRINT*

*For additional information on our $\mathrm{Pb}-$ Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| DOCUMENT NUMBER: | 98AON79919E | Electronic versions are uncontrolled except when accessed directly from the Document Repository. <br> Printed versions are uncontroled except when stamped "CONTROLLED COPY" in red. |
| ---: | :--- | :--- | :--- |
| DESCRIPTION: | WLCSP4, 0.76X0.76 | PAGE 1 OF 1 |

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